



07/17/2014

July 2014

Dear Customer,

Please be informed that Microchip will be migrating manufacturing material from gold to copper for the following products starting in August of 2014. Attached are the CPNs provided to the market back in 2012.

Current CPN	New Gold Material CPN
LAN8700IC-AEZG	LAN8700IC-AEZG-CAG
LAN8700IC-AEZG-TR	LAN8700IC-AEZG-TR-CAG
LAN9303M-AKZE	LAN9303M-AKZE-CAG
LAN9513I-JZX	LAN9513I-JZX-CAG
USB2251I-NU-06	USB2251I-NU-06-CAG
USB2517I-JZX	USB2517I-JZX-CAG
USB2641I-HZH-02	USB2641I-HZH-02-CAG
USB3300-EZK	USB3300-EZK-CAG
USB3300-EZK-TR	USB3300-EZK-TR-CAR
USB3319C-CP-TR	USB3319C-CP-TR-CAG
USB3316C-CP-TR	USB3316C-CP-TR-CAG

There are no plans to change the Part Number for these identified devices. Copper samples are available for customer system validation if necessary through request via the NSCAR system. We are sending this reminder as part of our internal alignment of processes within the rest of USB and LAN product line. This migration should have been complete before Microchip's acquisition of SMSC in 2012.

Customers impacted by this notice are advised to place last time buy orders as follows:

- Last date for booking Gold Material under standard CPN is August 15th, 2014
- Last date for shipment of Gold Material under standard CPN will be when last Gold orders under standard CPN are fulfilled or depletion of current Gold stock (whichever comes last).
- **Customers that want to continue to receive Gold Material can do so under a NEW Part Number (see table above). Note, that there will be an increase in unit price (10%) for the Gold Material going forward.**

The replacement parts described in this notice do not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Thank you for your continued support of Microchip.

If you have any questions or concerns, please do not hesitate to ask.

Regards,

A handwritten signature in black ink, appearing to read 'Mark Gordon', with a stylized flourish at the end.

Mark Gordon
UNG Marketing
Microchip Technology, Inc.



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Date: 08/09/2011

PCN-2011-106

Product Change Notification

Title: Transition of Copper Wire as qualified bond wire material

Part # Affected: LAN9115-MT; LAN9116-MT; LAN9117-MT; LAN9118-MT; LAN91C111-NS; LAN91C111-NU; LAN91C111I-NS; LAN91C111I-NU; LAN91C113-NS; LAN91C113-NU; LAN9220-ABZJ; LAN9221-ABZJ; LAN9221I-ABZJ; LAN9303-ABZJ; LAN9303-AKZE; LAN9303I-ABZJ; LAN9303I-AKZE; LAN9303M-AKZE; LAN9303MI-AKZE; LAN9420-NU; LAN9420I-NU; LAN9512-JZX; LAN9512I-JZX; LAN9513-JZX; LAN9513-JZX-TR; LAN9513I-JZX; LAN9514-JZX; LAN9514I-JZX

Part Data: No change to datasheets

Means of distinguishing changed parts: SMSC will be able to provide material traceability through lot numbers

Technical Information Contact: Brendan McKenna; Tactical Marketing

PCN Schedule/Dates:

Description	Date
Estimated Date of Implementation:	09/09/2011
Sample Availability:	Qualification Samples available 30 days after request
PCIN Issued:	08/04/2011

Change Information:

Description of Change Transition to copper wire as a qualified material for assembly.

Reason For Change Copper wire bonding continues to increase in supply chain providing flexibility and continuity of supply.

Was / Is List

Was: Gold (Au)	Is: Copper (Cu)
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Dependent Information:

Reliability Qualification Plan:	Attached
Die Shrink Details:	N/A
Design Changes:	N/A
Electrical Differences:	N/A
Mechanical Differences:	N/A



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Date: 04/09/2012

PCN-2012-115

Product Change Notification

Title: Transition to Copper Wire as a qualified wire bond material

Part # Affected: EMC1438-1-AP; EMC1438-1-AP-TR; EMC2103-1-KP; EMC2103-1-KP-TR; LAN8700C-AEZG; LAN8700C-AEZG-TR; LAN8700IC-AEZG; LAN8700IC-AEZG-TR; SCH5627-NS; USB2240-AEZG-06; USB2240I-AEZG-06; USB2241-AEZG-06; USB2241I-AEZG-06; USB2244-AEZG-06; USB2244I-AEZG-06; USB2250-NU-06; USB2250I-NU-06; USB2251-NU-06; USB2251I-NU-06; USB2640-HZH-02; USB2640I-HZH-02; USB2640I-HZH-02-TR; USB2641-HZH-02; USB2641I-HZH-02; USB2649-HZH; USB3280-AEZG; USB3280-AEZG-TR; USB3300-EZK; USB3300-EZK-TR; USB3311C-CP; USB3311C-CP-TR; USB3313C-CP; USB3313C-CP-TR; USB3315C-CP; USB3315C-CP-TR; USB3316C-CP; USB3316C-CP-TR; USB3317C-CP; USB3317C-CP-TR; USB3318C-CP; USB3318C-CP-TR; USB3319C-CP; USB3319C-CP-TR; USB3320C-EZK; USB3320C-EZK-TR; USB3340-EZK; USB3340-EZK-TR

Part Data: No change to datasheets

Means of distinguishing changed parts: SMSC will be able to provide material traceability through lot numbers

Technical Information Contact: Brendan McKenna; Tactical Marketing

PCN Schedule/Dates:

Description	Date
Estimated Date of Implementation:	7/9/2012
Sample Availability:	Qualification Samples available 30 days after request

SMSC customers are required to get back to SMSC sales team within 30 days after receipt of this PCN (or the earlier, the better) with any issues, concerns, requests for extensions in regards to this PCN and with request for the samples.

Change Information:

Description of Change Transition to copper wire as a qualified material for assembly.

Reason For Change

Copper wire bonding continues to increase in supply chain providing flexibility and continuity of supply.

Was / Is List**Was:**

Gold (Ag); 0.7-1.0 mil

Is:

Copper (Cu); 0.8 mil

Dependent Information:**Reliability Qualification Plan:**

Attached

Die Shrink Details:

N/A

Design Changes:

N/A

Electrical Differences:

N/A

Mechanical Differences:

N/A